

Advanced Power MOSFET

IRFM214A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 250V$
- Lower $R_{DS(on)}$: 1.393 Ω (Typ.)

$BV_{DSS} = 250 V$

$R_{DS(on)} = 2.0 \Omega$

$I_D = 0.64 A$

SOT-223



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	250	V
I_D	Continuous Drain Current ($T_A=25^\circ C$)	0.64	A
	Continuous Drain Current ($T_A=70^\circ C$)	0.51	
I_{DM}	Drain Current-Pulsed	① 5	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	② 51	mJ
I_{AR}	Avalanche Current	① 0.64	A
E_{AR}	Repetitive Avalanche Energy	① 0.21	mJ
dv/dt	Peak Diode Recovery dv/dt	③ 4.8	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ C$)*	2.1	W
	Linear Derating Factor *	0.017	$W/\text{ }^\circ C$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient *	--	60	$^\circ C/W$

* When mounted on the minimum pad size recommended (PCB Mount).

SAMSUNG

ELECTRONICS

IRFM214A

N-CHANNEL
POWER MOSFET

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	250	--	--	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.29	--	$\text{V}/^\circ\text{C}$	$I_D=250\mu\text{A}$ See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=5\text{V}, I_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$V_{GS}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$V_{GS}=-30\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS}=250\text{V}$
		--	--	100		$V_{DS}=200\text{V}, T_A=125^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	2.0	Ω	$V_{GS}=10\text{V}, I_D=0.32\text{A}$ ④
g_{fs}	Forward Transconductance	--	0.64	--	O	$V_{DS}=40\text{V}, I_D=0.32\text{A}$ ④
C_{iss}	Input Capacitance	--	180	230	pF	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	35	43		
C_{rss}	Reverse Transfer Capacitance	--	14	18		
$t_{d(on)}$	Turn-On Delay Time	--	10	30	ns	$V_{DD}=125\text{V}, I_D=2.8\text{A}, R_G=24\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	11	30		
$t_{d(off)}$	Turn-Off Delay Time	--	22	55		
t_f	Fall Time	--	14	40		
Q_g	Total Gate Charge	--	8.5	12	nC	$V_{DS}=200\text{V}, V_{GS}=10\text{V}, I_D=2.8\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	1.8	--		
Q_{gd}	Gate-Drain ("Miller") Charge	--	3.9	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	0.64	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	5		
V_{SD}	Diode Forward Voltage ④	--	--	1.5	V	$T_J=25^\circ\text{C}, I_s=0.64\text{A}, V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	112	--	ns	$T_J=25^\circ\text{C}, I_F=2.8\text{A}$
Q_{rr}	Reverse Recovery Charge	--	0.35	--	μC	$di_F/dt=100\text{A}/\mu\text{s}$ ④

Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=200\text{mH}, I_{AS}=0.64\text{A}, V_{DD}=50\text{V}, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- ③ $I_{SD} < 2.8\text{A}, di/dt < 130\text{A}/\mu\text{s}, V_{DD} < BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width = $250\ \mu\text{s}$, Duty Cycle $< 2\%$
- ⑤ Essentially Independent of Operating Temperature

**N-CHANNEL
POWERMOSFET**

IRFM214A

Fig 1. Output Characteristics

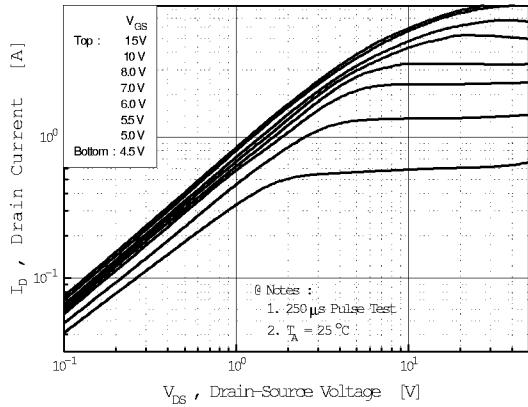


Fig 2. Transfer Characteristics

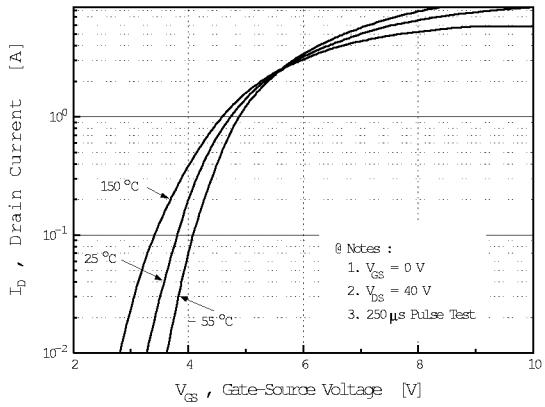


Fig 3. On-Resistance vs. Drain Current

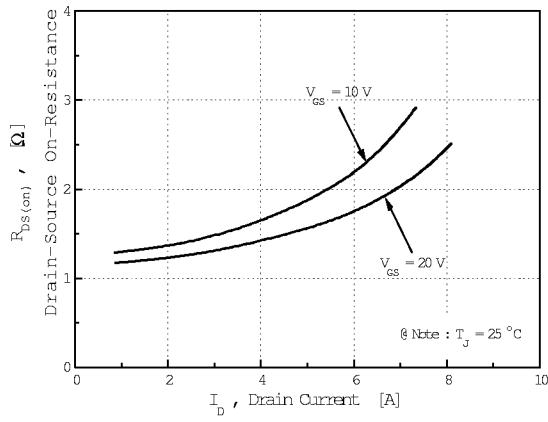


Fig 4. Source-Drain Diode Forward Voltage

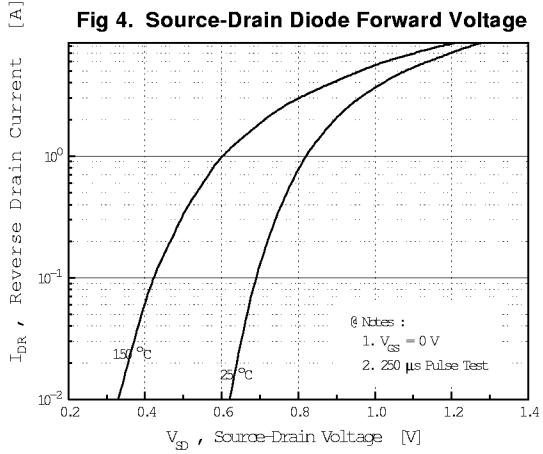


Fig 5. Capacitance vs. Drain-Source Voltage

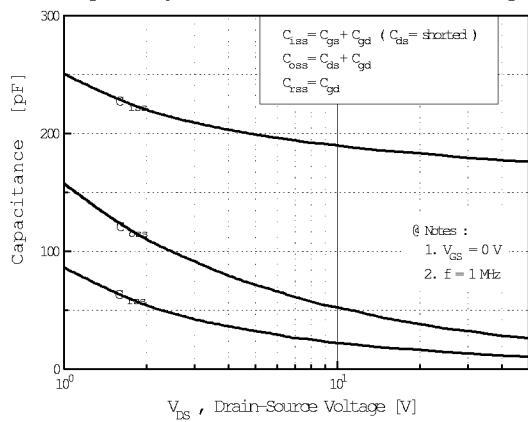
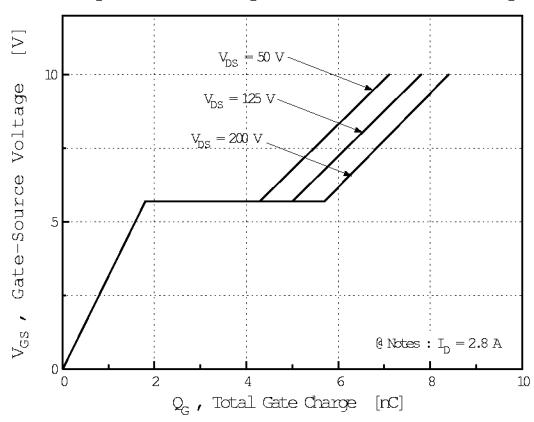


Fig 6. Gate Charge vs. Gate-Source Voltage



IRFM214A

N-CHANNEL
POWER MOSFET

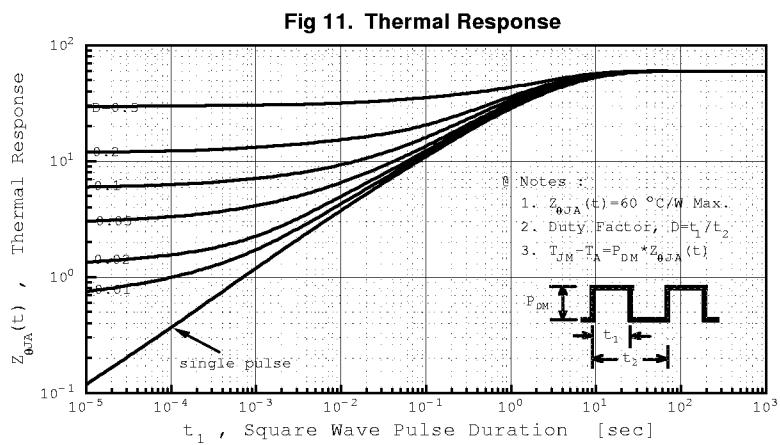
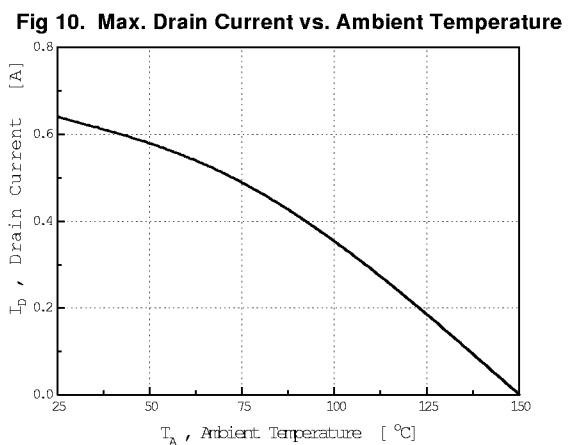
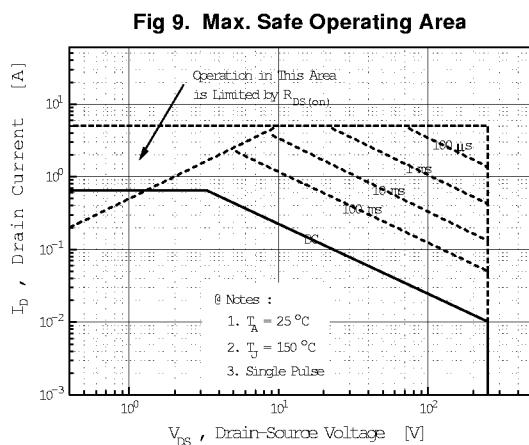
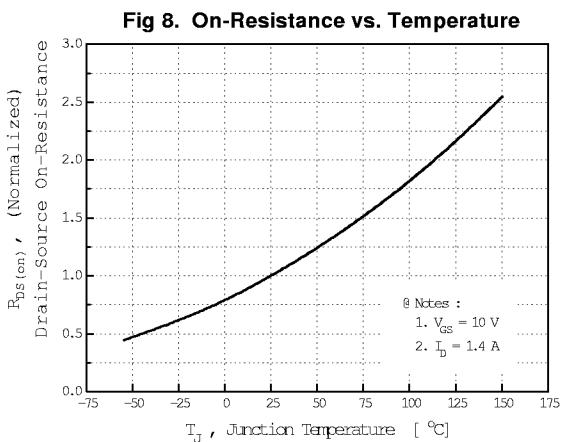
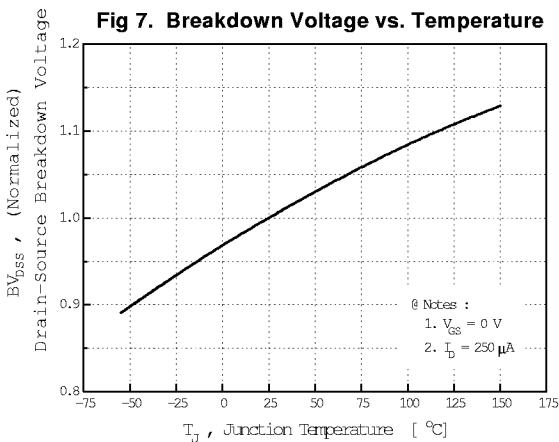


Fig 12. Gate Charge Test Circuit & Waveform

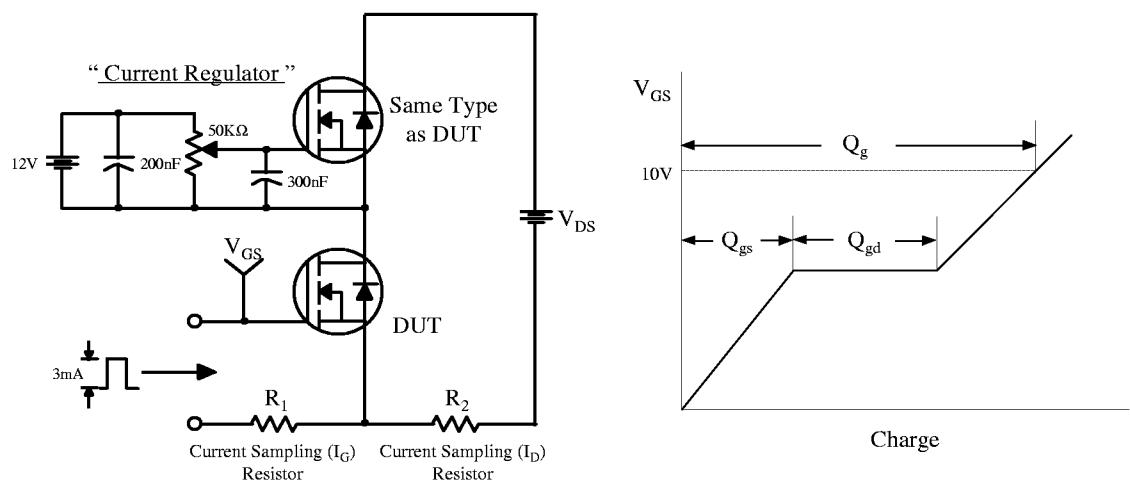


Fig 13. Resistive Switching Test Circuit & Waveforms

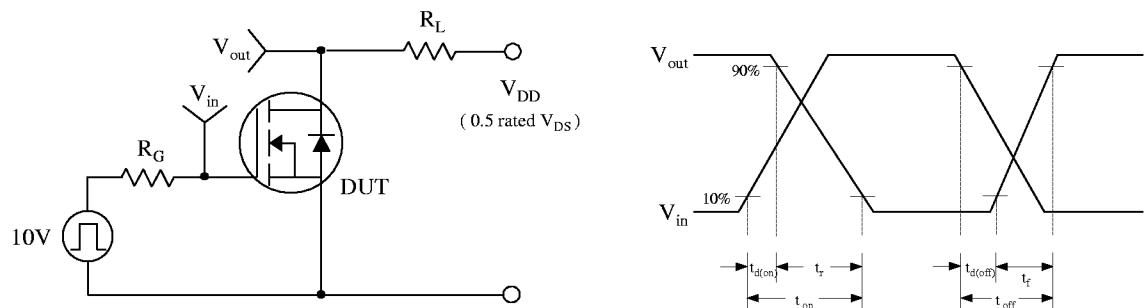
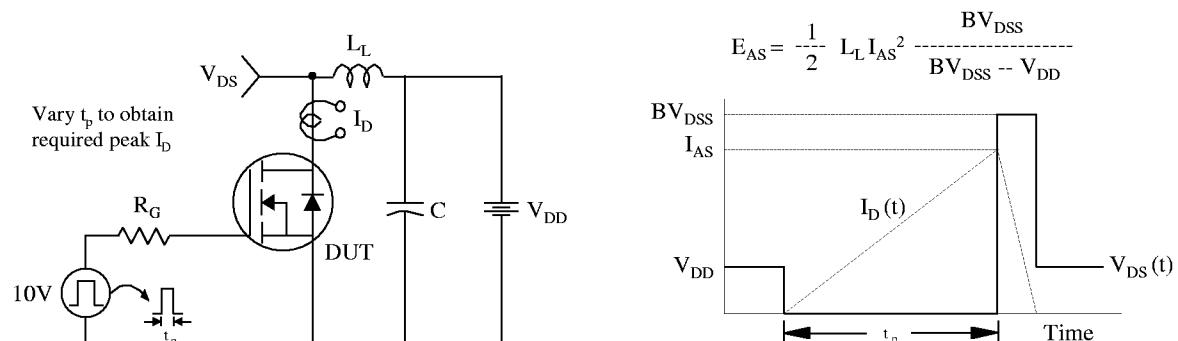


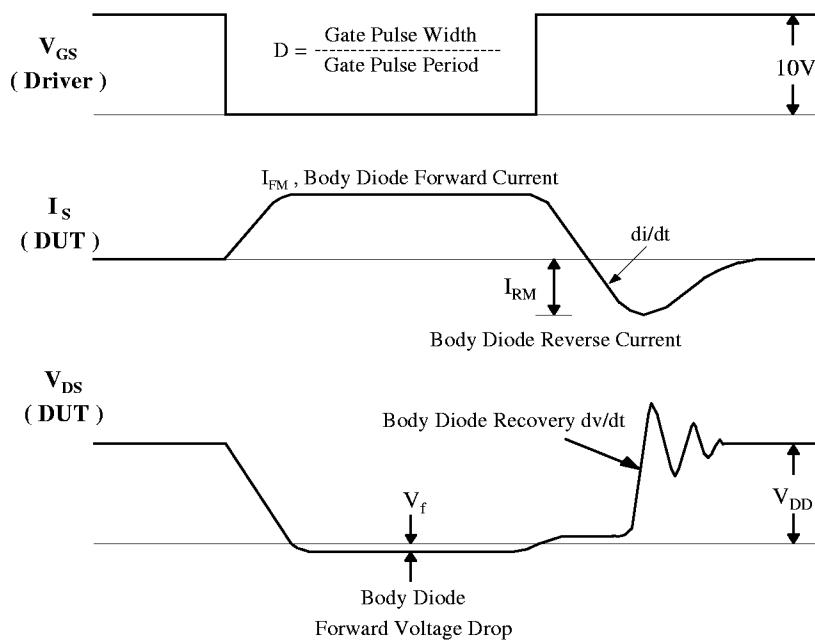
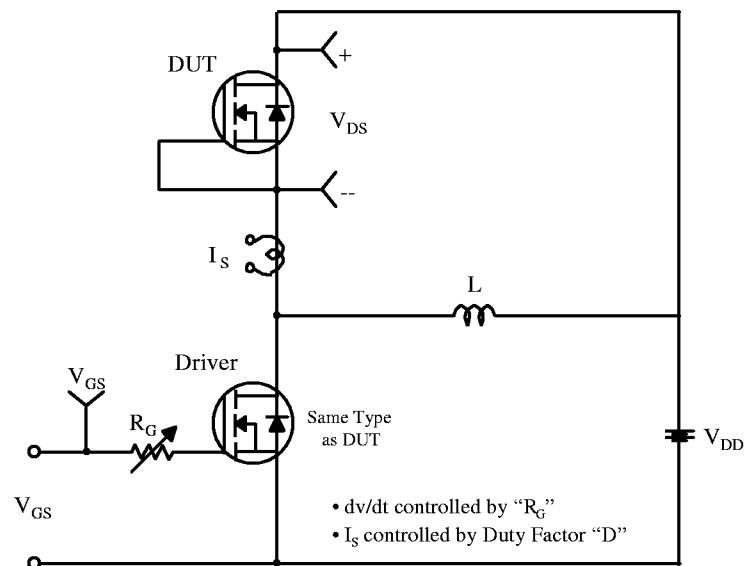
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



IRFM214A

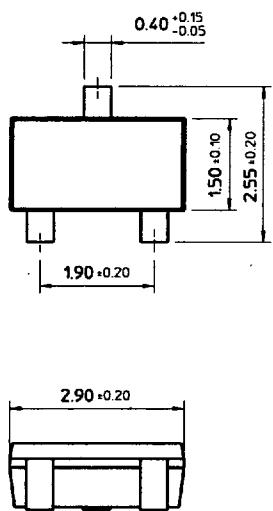
N-CHANNEL
POWER MOSFET

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

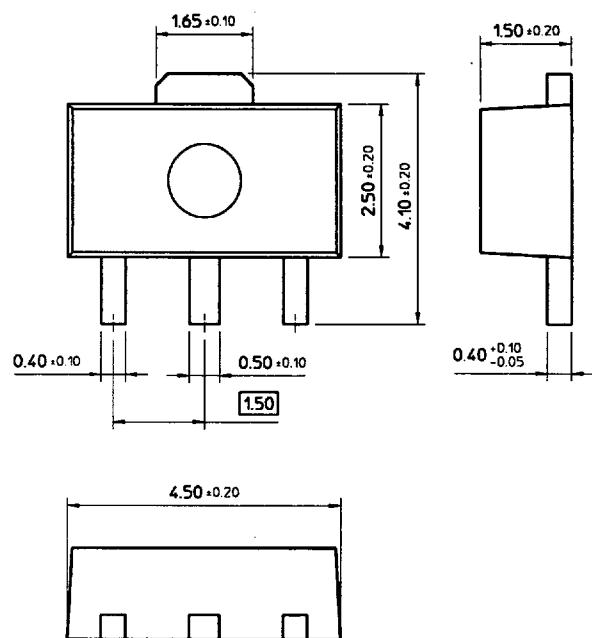


Dimensions in Millimeters

SOT-23



SOT-89



SOT-223

